

## INTRODUCTION

Molex's latest Micro PGA sockets are designed to accept Mobile Pentium\* 4 and Mobile Celeron\* Processor-M series for applications such as thin notebooks and blade servers. These high-density sockets feature low profiles and proven Ball Grid Array (BGA) soldering technology for stable PCB processing.

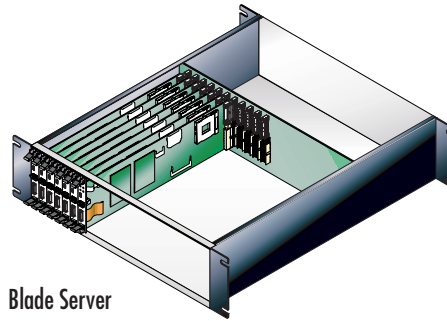
The new sockets include an easy-to-use cam mechanism and stainless steel cam retainer to prevent wear-and-tear on the housing during use. The terminal includes a dual-beam chamfered contact for good electrical performance, and BGA-interface design to ensure good thermal mismatch control between components and the PCB.

Molex's Micro PGA sockets are part of our growing family of innovative socketing solutions for processor, memory and test applications.

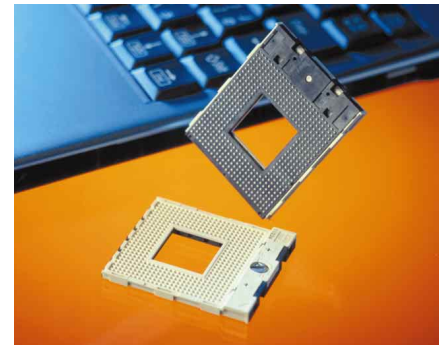


# Micro PGA Socket 478/479 Circuits For Mobile Pentium\* 4 ZIF Type, BGA Mount

**Applications:**  
Notebook PCs  
Blade Servers

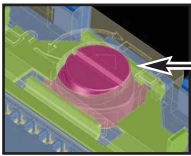


Blade Server

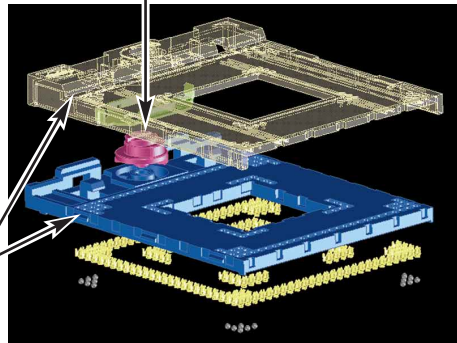


\*Pentium and Celeron are registered trademarks of Intel Corporation

## FEATURES AND BENEFITS

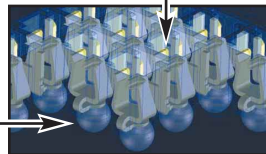


Stainless steel cam retainer protects plastic cover from wear.



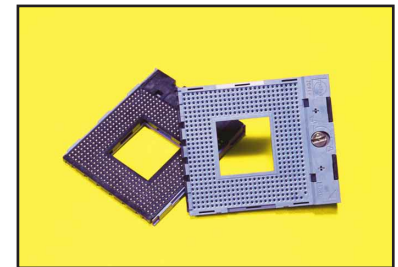
LCP housing and cover with profile height of 3.30mm (.130")

Dual-beam chamfered contact design provides low insertion force and good electrical performance.



Ball Grid Array (BGA) solder balls are self-centering and avoid the problem of bent tails.

**New!** *Blue Color Version For Centrino\* Mobile Technology Processors*



Accepts energy-saving Pentium mobile processors  
For notebooks, blade servers and small desktop PCs  
478 circuits

Small pin layout difference and blue color to differentiate from standard P4-M socket  
Same features as standard P4-M socket

Order No.: 500210-4784

\*Centrino is a trademark of Intel Corporation

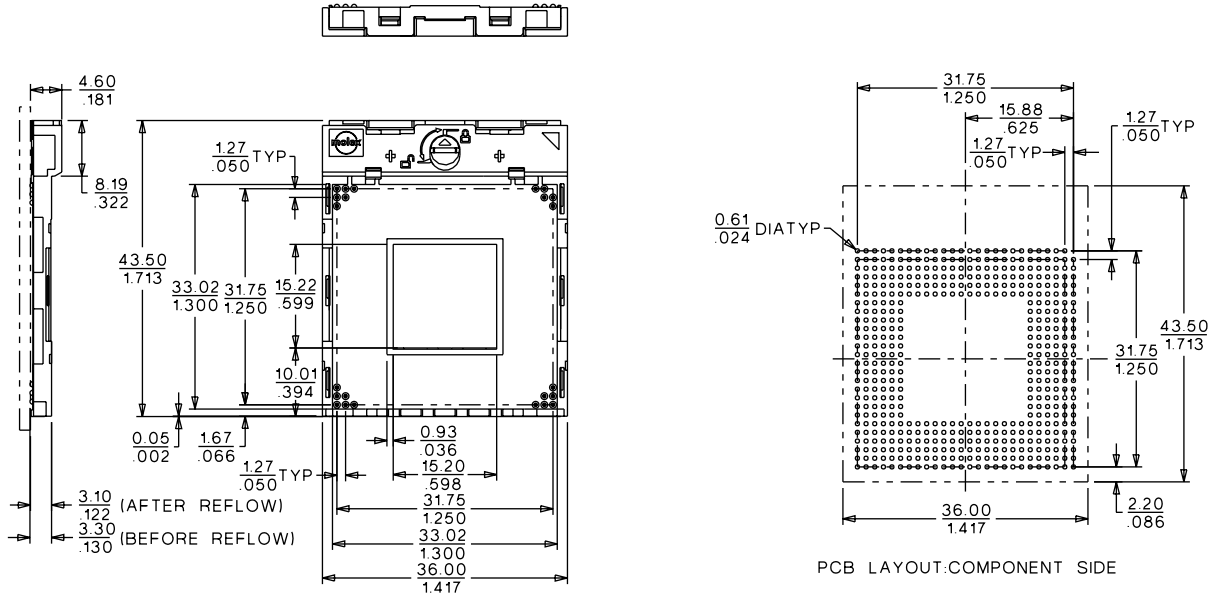
## SPECIFICATIONS

Physical	Housing	Black LCP, UL 94V-0
	Contact	Copper Alloy
	Solder Ball	Tin/Lead, 0.76mm (.030") dia.
	CAM	Stainless Steel
	CAM Holder	Stainless Steel
	Plating—Contact Area	Gold
	Underplating	Nickel
	Operating Temperature	-20 to +90°C

Electrical	Voltage	100V
	Current	0.5A
	Contact Resistance	25 milliohms max.
	Dielectric Withstanding Voltage	AC 360V
	Insulation Resistance	800 Megohms min.
Mechanical	Durability	50 cycles
Reference	Product Specification	PS-51248-005
	Packaging	Hard Tray/ Embossed Tape
	Designed In	Millimeters



**Micro PGA Socket  
478/479 Circuits  
For Mobile Pentium\* 4  
ZIF Type, BGA Mount**



**ORDERING INFORMATION**

Circuits	Order No.	
	Hard Tray	Embossed Tape
478	51248-4782	51248-4784
479	51248-4792	51248-4794



Bringing People & Technology Together, Worldwide<sup>SM</sup>

**Americas Headquarters**

Lisle, Illinois 60532 U.S.A.  
Tel: 1-800-78MOLEX  
amerinfo@molex.com

**Far East North Headquarters**

Yamato, Kanagawa, Japan  
Tel: 81-462-65-2324  
feninfo@molex.com

**Far East South Headquarters**

Jurong, Singapore  
Tel: 65-6268-6868  
fesinfo@molex.com

**European Headquarters**

Munich, Germany  
Tel: 49-89-413092-0  
eurinfo@molex.com

**Corporate Headquarters**

2222 Wellington Court  
Lisle, Illinois 60532 U.S.A.  
Tel: 630-969-4550  
amerinfo@molex.com

Visit our Web site at <http://www.molex.com>